

L Number	Hits	Search Text	DB	Time stamp
85	76	distance with (template and (substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/13 14:15
86	550	pattern\$2 near template and (substrate or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/13 14:43
88	16	gap with (pattern\$2 near template and (substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/13 14:44
89	33	determin\$3 with (pattern\$2 near template and (substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/13 14:45
90	86	(pattern\$2 near template and (substrate or wafer)) and distance and gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/13 14:45
91	18	((pattern\$2 near template and (substrate or wafer)) and distance and gap) and light near reflect\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/13 14:45
92	84	gap with (template and (substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/13 14:46
93	84	gap with (template and (substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/13 14:46
87	44	(measur\$3 or determin\$4) with (pattern\$2 near template and (substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/13 14:46